# **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(on)TYP</sub>	I <sub>D</sub>	
100V	3.9mΩ@10V	130A	



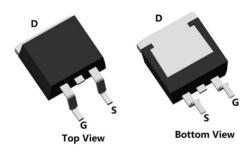
#### **Feature**

- Fast Switching
- Low Gate Charge and Rdson
- Advanced Split Gate Trench Technology
- 100% Single Pulse avalanche energy Test

## **Applications**

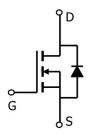
- Power switching application
- DC-DC Converter
- Power Management

### **Package**

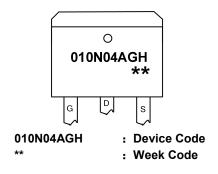


TO-263(1:G 2:D 3:S)

## Circuit diagram



## Marking



#### **Order Information**

Device	Package	Unit/Tape	
SP010N04AGHTD	TO-263	800	

100V N-Channel Power MOSFET

# Absolute maximum ratings (Ta=25°C,unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V <sub>DS</sub>	100	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current (Tc=25°C)	I <sub>D</sub>	130	Α
Continuous Drain Current (Tc=100°C)	I <sub>D</sub>	90	Α
Pulsed Drain Current	I <sub>DM</sub>	520	Α
Single Pulse Avalanche Energy <sup>1</sup>	Eas	841	mJ
Power Dissipation (Tc=25°C)	P <sub>D</sub>	180	W
Thermal Resistance Junction-to-Case	R <sub>eJC</sub>	0.69	°C/W
Storage Temperature Range	T <sub>STG</sub>	-55 to 150	$^{\circ}$
Operating Junction Temperature Range	TJ	-55 to 150	$^{\circ}$ C

# Electrical characteristics (Ta=25°C, unless otherwise noted)

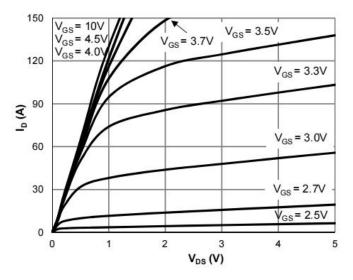
Characteristics	Symbol	Test Condition	Min	Тур	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	ID = 250µA, VGS = 0V	100	-	-	V
Drain Cut-Off Current	I <sub>DSS</sub>	VDS = 80V, VGS = 0V	-	-	1	uA
Gate Leakage Current	I <sub>GSS</sub>	VGS = ±20V, VDS = 0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	VDS = VGS, ID = 250μA	2	3	4	V
Drain-Source ON Resistance	R <sub>DS(ON)</sub>	VGS = 10V, ID = 30A	-	3.9	5.2	mΩ
Dynamic Characteristics						
Input Capacitance	Ciss		-	4251	-	
Output Capacitance	Coss	VDS =50V, VGS = 0V, f = 1.0MHz	-	658	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	26	-	
Total Gate Charge	Qg		-	69	-	nC
Gate-Source Charge	Q <sub>gs</sub>	VDS=50V , VGS=10V , ID=20A	-	24	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	18	-	
Switching Characteristics			•	•	•	
Turn-On Delay Time	t <sub>d(on)</sub>		-	12	-	
Rise Time	t <sub>r</sub>	VGS = 10V, VDS = 50V, RL=2.5Ω ,	-	23	-	
Turn-Off Delay Time	t <sub>d(off)</sub>	RG = 3.0Ω	-	37	-	nS
Fall Time	t <sub>f</sub>		-	16	-	]
Drain-Source Body Diode Characteri	stics					
Source-Drain Diode Forward Voltage	V <sub>SD</sub>	VGS=0V , IS=1A , TJ=25℃	-	-	1.2	V
Maximum Body-Diode Continuous Current	Is		-	-	130	Α
Reverse Recovery Time	Trr	I <sub>S</sub> =20A, di/dt=100A/us, TJ=25℃		65	-	nS
Reverse Recovery Charge	Qrr			126	-	nC

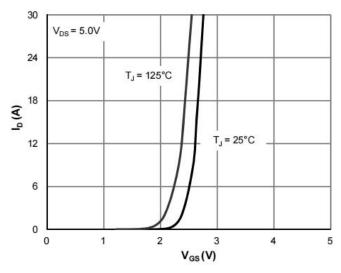
#### Note:

1. The EAS test condition is VDD=50V,VGS=10V,L=0.5mH,RG=25Ω



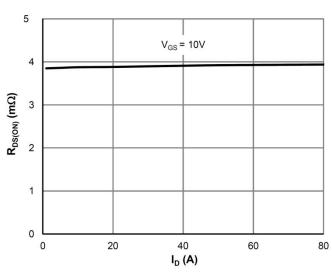
## **Typical Characteristics**

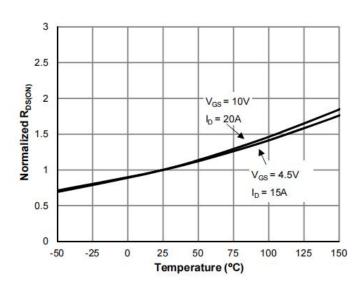




**Typical Output Characteristics** 

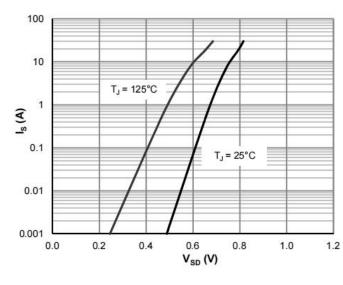


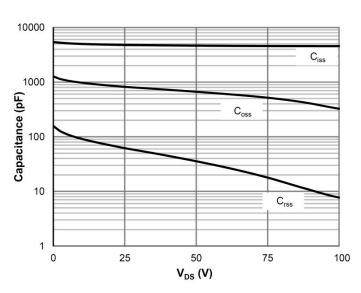




**On-Resistance vs.Drain Current** 

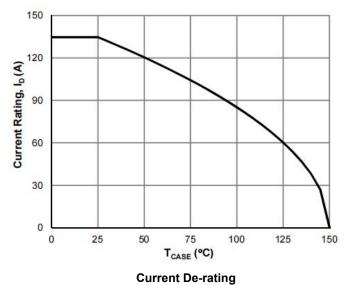
On-Resistance vs. Junction Temperature

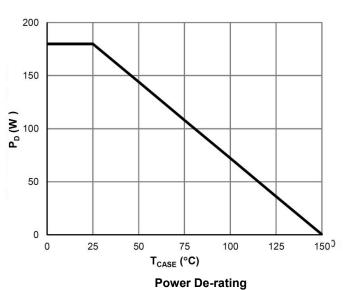


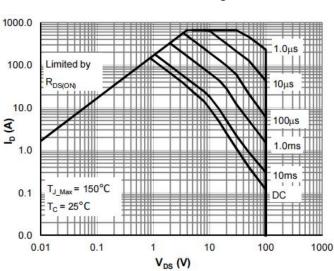


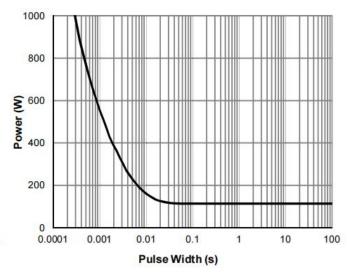
**Body-Diode Characteristics** 

**Capacitance Characteristics** 



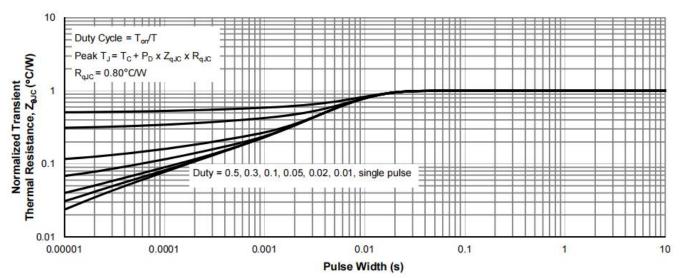






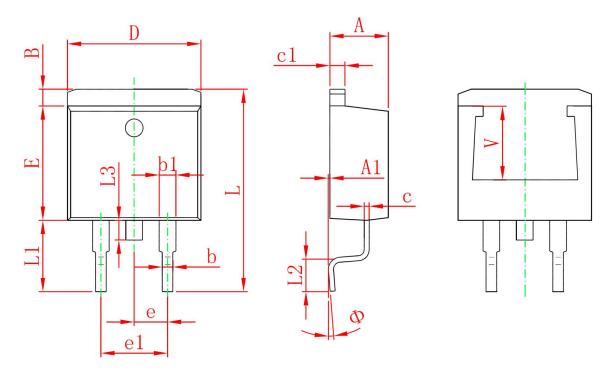
**Maximum Safe Operating Area** 

Single Pulse Power Rating, Junction-to-Case



**Normalized Maximum Transient Thermal Impedance** 





	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	4.470	4.670	0.176	0.184	
A1	0.000	0.150	0.000	0.006	
В	1.120	1.420	0.044	0.056	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.310	0.530	0.012	0.021	
c1	1.170	1.370	0.046	0.054	
D	10.010	10.310	0.394	0.406	
E	8.500	8.900	0.335	0.350	
е	2.540	2.540 TYP.		TYP.	
e1	4.980	5.180	0.196	0.204	
L	14.940	15.500	0.588	0.610	
L1	4.950	5.450	0.195	0.215	
L2	2.340	2.740	0.092	0.108	
L3	1.300	1.700	0.051	0.067	
Ф	0°	8°	0°	8°	
V	5.600 REF.		0.220 REF.		